



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1812-01** Date: December 14, 2018
Product Affected: SOIC-8
(Refer to attachment 2 for affected part numbers)

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark
 Back Mark Lot # will have a "GR" prefix
 Date Code
 Other

Date Effective: March 14, 2019

Contact: IDT PCN DESK

Attachment: Yes No

E-mail: pcndesk@idt.com

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|---|---|
| <input type="checkbox"/> Die Technology
<input type="checkbox"/> Wafer Fabrication Process
<input type="checkbox"/> Assembly Process
<input type="checkbox"/> Equipment
<input checked="" type="checkbox"/> Material
<input type="checkbox"/> Testing
<input checked="" type="checkbox"/> Manufacturing Site
<input type="checkbox"/> Data Sheet
<input type="checkbox"/> Other | <p>This notification is to advise our customers that IDT is adding Greatek, Taiwan as an alternate assembly facility.</p> <p>There is no change to the moisture performance rating.</p> <p>Please refer to Attachment 1 for the qualification summary and material set details.
Please refer to Attachment 2 for affected part# list.</p> |
|---|---|

RELIABILITY/QUALIFICATION SUMMARY:

Qualification has been successfully completed. There is no change in MSL rating.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE _____



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ATTACHMENT 1 - PCN # : A1812-01

PCN Type: Alternate Assembly Location & Change of material sets

Data Sheet Change: N/A

Detail Of Change:

This notification is to advise our customers that IDT is adding Greatek, Taiwan as an alternate assembly facility.

The material set details of the current and alternate Assembly locations is shown in the tables below. The die attach, mold compound and bonding wire used at the alternate assembly sites are qualified IDT materials. There is no change from the existing qualified lead frame material and lead finish for these alternate assembly sites.

There is no change to the moisture performance rating but the material declaration will differ.

Qualified Material Sets, by Assembly Subcontractor

Material Set / Assembly	Existing			Alternate
	ATP - Amkor, Philippines	OSET- Orient Semiconductor, Taiwan	UTL - UTAC, Thailand	GEI - Greatek, Taiwan
Die Attach	Ablestik 8290	EN4900GC	Ablestik 2200	CRM-1076DJ-G
Bonding Wire	Gold wire	Gold wire	Gold wire	Gold wire
Mold Compound	EME-G600	CEL-9220HF	EME-G600	EME-G700H



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ATTACHMENT 1 - PCN # : A1812-01

Qualification Information and Qualification Data:

Affected Packages: SOIC-8

Assembly Material: The affected package type is using the respective subcon standard materials as shown on page 1 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests

Qualification Vehicle: SOIC-8 (3 lots)

Test Description	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
¹ HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0 / 25	0 / 25	0 / 25
¹ HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0 / 25	0 / 25	0 / 25
¹ Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0 / 25	0 / 25	0 / 25
High Temperature Storage Test (150°C, 1000 hours)	JESD22-A103	0 / 25	0 / 25	0 / 25
Ball Shear Test	JESD22-B116	0 / 5	0 / 5	0 / 5
Bond Pull Test	MIL-STD-883, M 2011	0 / 5	0 / 5	0 / 5
X-ray Examination	MIL-STD-883, M 2015	0 / 45	0 / 45	0 / 45

Notes: 1. Subjected to Preconditioning per JESD22-A113 for MSL 1



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 2 - PCN # : A1812-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
252MI-47LFT	343M-59LF	251M-37LFT	252M-51LFT
252PMLFT	343M-59LFT	251M-38LF	252M-55LF
341-42MIPLF	343M-60LF	251M-38LFT	252M-55LFT
341-42MIPLFT	343M-60LFT	251MI-34LF	252M-62LF
341-42MPLF	343M-61LF	251MI-34LFT	252M-62LFT
341-42MPLFT	343M-61LFT	251MI-38LF	252MI-31LF
341M-33LF	343M-62LF	251MI-38LFT	252MI-31LFT
341M-33LFT	343M-62LFT	251PMILF	252MI-32LF
341MIPLF	343MI-31LF	251PMILFT	252MI-32LFT
341MIPLFT	343MIPLF	251PMLF	252MI-33LFT
341MPLF	343MIPLFT	251PMLFT	252MI-45LF
341MPLFT	343MPLF	252M-08LFT	252M-49LFT
342M-17LF	343M-53LFT	251M-37LF	252M-49LF
252PMLF	343M-53LF	251M-35LFT	252M-24LFT
252PMILFT	342M-30LFT	251M-07LFT	252M-25LFT
252MI-48LF	342M-32LFT	251M-21LF	252M-26LF
252MI-48LFT	342MI-34LF	251M-21LFT	252M-26LFT
252MI-50LF	342MI-34LFT	251M-22LF	252M-42LF
252MI-50LFT	342MIPLF	251M-22LFT	252M-42LFT
252MI-52LF	342MIPLFT	251M-29LF	252M-43LF
252MI-52LFT	342MPLF	251M-29LFT	252M-43LFT
252MI-53LF	342MPLFT	251M-30LF	252M-44LF
252MI-53LFT	343M-34LFT	251M-30LFT	252M-44LFT
252MI-65LF	343M-39LFT	251M-33LF	252M-46LF
252MI-65LFT	343M-48LF	251M-33LFT	252M-46LFT
252MI-66LF	343M-48LFT	251M-35LF	252MI-45LFT
252PMILF	343MPLFT	252M-23LF	
342M-17LFT	252MI-47LF	252M-23LFT	
342M-30LF	251M-07LF	252M-51LF	